

**• General Description**

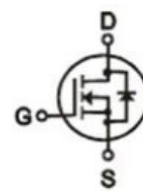
The ZM027N03I combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ . This device is ideal for load switch and battery protection applications.

**• Features**

- Advance high cell density Trench technology
- Low  $R_{DS(ON)}$  to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

**• Application**

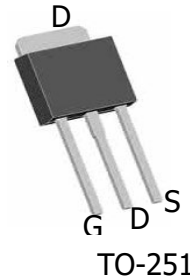
- MB/VGA Vcore
- SMPS 2<sup>nd</sup> Synchronous Rectifier
- POL application
- BLDC Motor driver

**• Product Summary**


$V_{DS} = 30V$

$R_{DS(ON)} = 2.7m\Omega$

$I_D = 95A$


**• Ordering Information:**

Part NO.	ZM027N03I
Marking	ZM027N03
Packing Information	REEL TAPE
Basic ordering unit (pcs)	900

**• Absolute Maximum Ratings ( $T_C = 25^\circ C$ )**

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_{D@T_C=25^\circ C}$	95	A
	$I_{D@T_C=75^\circ C}$	72	A
	$I_{D@T_C=100^\circ C}$	60	A
Pulsed Drain Current <sup>①</sup>	$I_{DM}$	220	A
Total Power Dissipation	$P_D@T_C=25^\circ C$	70	W
Total Power Dissipation	$P_D@T_A=25^\circ C$	2.8	W
Operating Junction Temperature	$T_J$	-55 to 175	$^\circ C$
Storage Temperature	$T_{STG}$	-55 to 175	$^\circ C$
Single Pulse Avalanche Energy ( $L=0.5mH, V_{GS}=10V, R_g=25\Omega, T_J=25^\circ C$ )	$E_{AS}$	350	mJ



Single Pulse Avalanche Energy ( $L=0.1\text{mH}$ , $V_{GS}=10\text{V}$ , $R_g=25\Omega$ , $T_J=25^\circ\text{C}$ )	$E_{AS}$	180	mJ
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**•Thermal resistance**

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	$R_{thJC}$	-	-	1.8	$^\circ\text{C/W}$
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	45	$^\circ\text{C/W}$
Soldering temperature, wave soldering for 10s	$T_{sold}$	-	-	265	$^\circ\text{C}$

**•Electronic Characteristics**

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	30			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	1.2		2.5	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=30\text{V}$ , $V_{GS}=0\text{V}$			1.0	$\mu\text{A}$
Gate- Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$			$\pm 100$	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS}=10\text{V}$ , $I_D=24\text{A}$		2.7	3.6	m $\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=12\text{A}$		4.6	5.5	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=25\text{V}$ , $I_D=10\text{A}$		30		S
Source-drain voltage	$V_{SD}$	$I_S=24\text{A}$			1.28	V

**•Dynamic Characteristics**

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	$C_{iss}$	$f = 1\text{MHz}$ , $V_{DS}=25\text{V}$	-	2800	-	pF
Output capacitance	$C_{oss}$		-	420	-	
Reverse transfer capacitance	$C_{rss}$		-	280	-	
Gate Resistance	$R_g$	$f = 1\text{MHz}$		2.5		$\Omega$
Total gate charge	$Q_g$	$V_{DD} = 25\text{V}$ $I_D = 8\text{A}$ $V_{GS} = 10\text{V}$	-	27	-	nC
Gate - Source charge	$Q_{gs}$		-	8.6	-	
Gate - Drain charge	$Q_{gd}$		-	13.8	-	
Turn-ON Delay time	$t_{D(on)}$	$V_{GS}=10\text{V}$ , $V_{DS}=15\text{V}$ $V$		12		ns
Turn-ON Rise time	$t_r$			44		ns
Turn-Off Delay time	$t_{D(off)}$			50		ns

Turn-Off Fall time	$t_f$	$R_G = 3.3\Omega, I_D = 15A$	15	ns
Reverse Recovery Time	$t_{RR}$	$V_{DD} = 20V,$ $dI_S/dt = 100A/\mu s,$ $I_S = 30A$	5.8	ns
Charge Time	$t_a$		3.4	ns
Discharge Time	$t_b$		2.4	ns
Reverse Recovery Charge	$Q_{RR}$		1.6	nC

Note: ① Pulse Test : Pulse width  $\leq 300\mu s$ , Duty cycle  $\leq 2\%$  ;

Fig.1 Power Dissipation

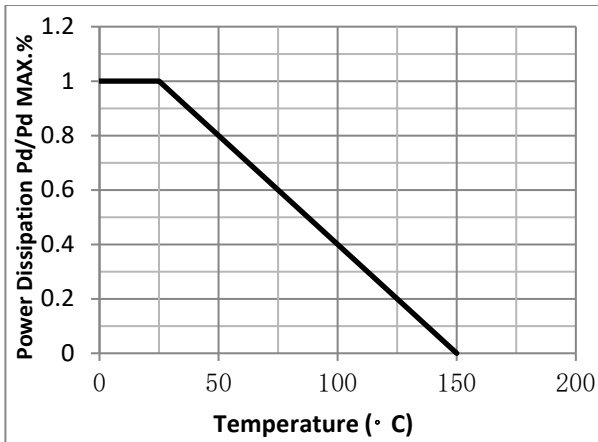


Fig.2 Typical output Characteristics

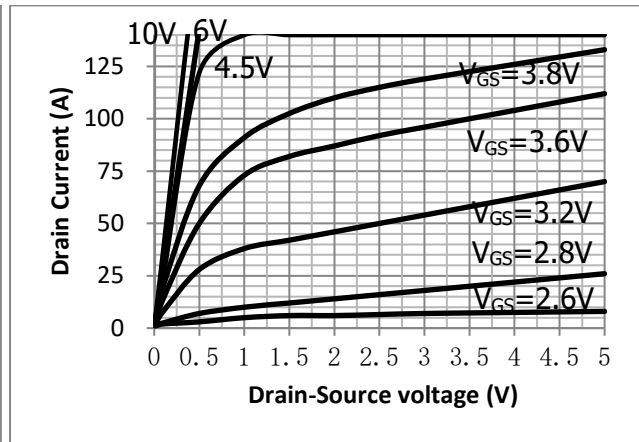


Fig.3 Threshold Voltage V.S Junction Temperature

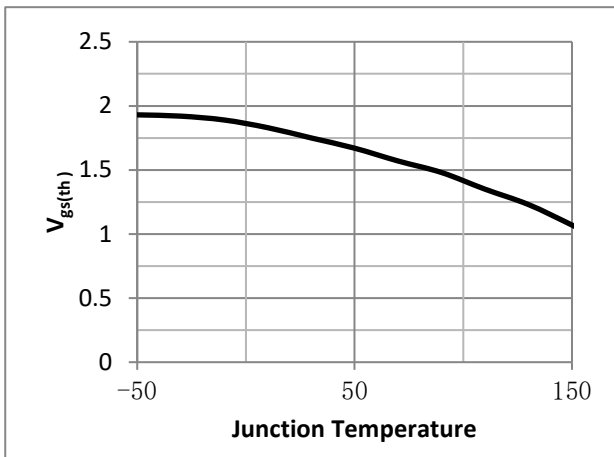


Fig.4 Resistance V.S Drain Current

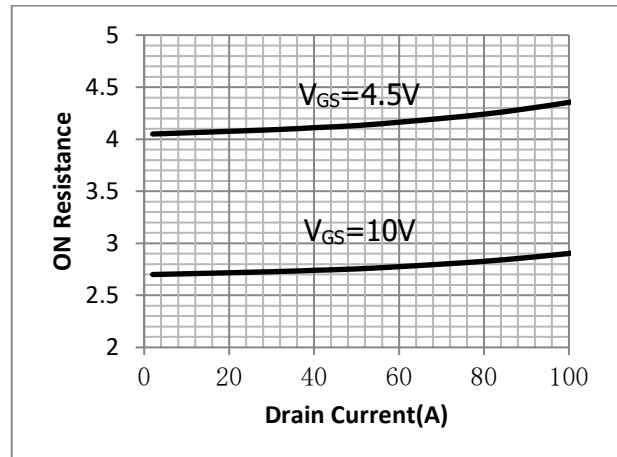


Fig.5 On-Resistance VS Gate Source Voltage

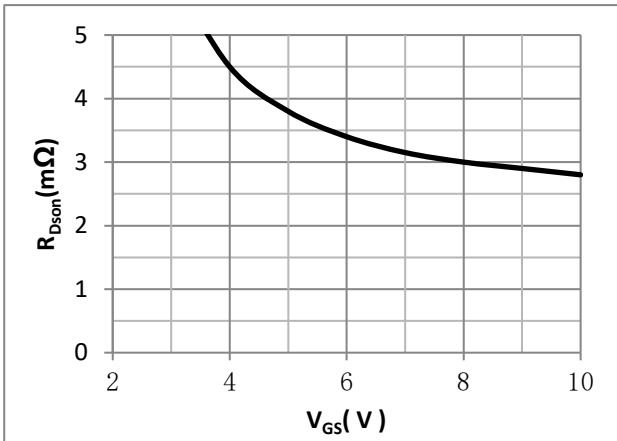


Fig.6 On-Resistance V.S Junction Temperature

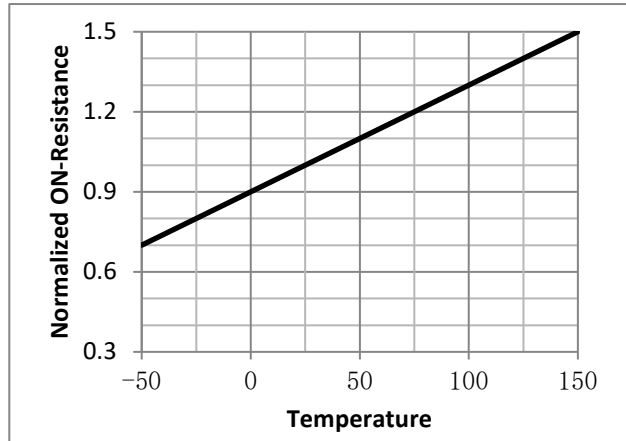


Fig.7 SOA Maximum Safe Operating Area

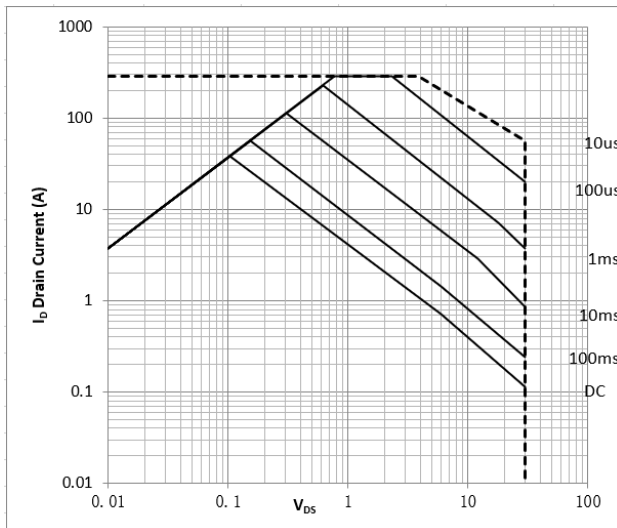


Fig.8 ID-Junction Temperature

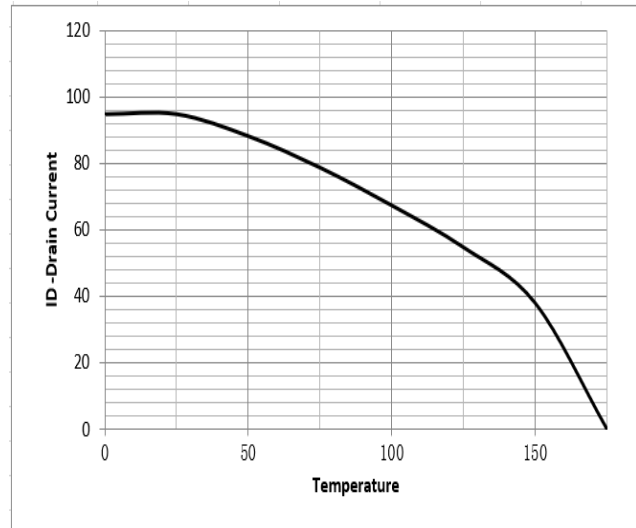


Figure 9. Diode Forward Voltage vs. Current

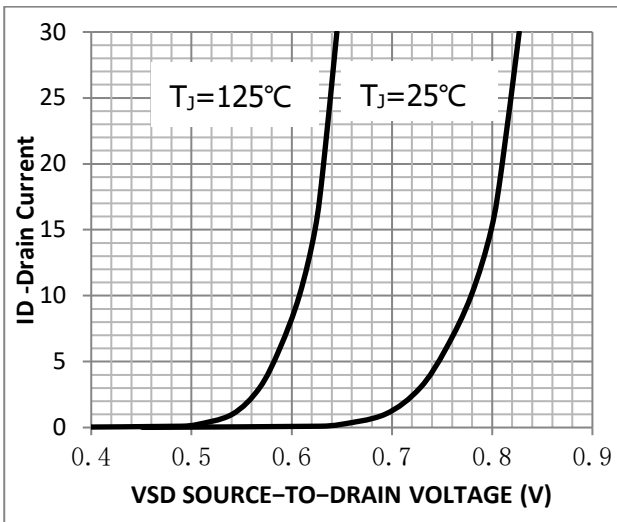


Figure 10. Transfer Characteristics

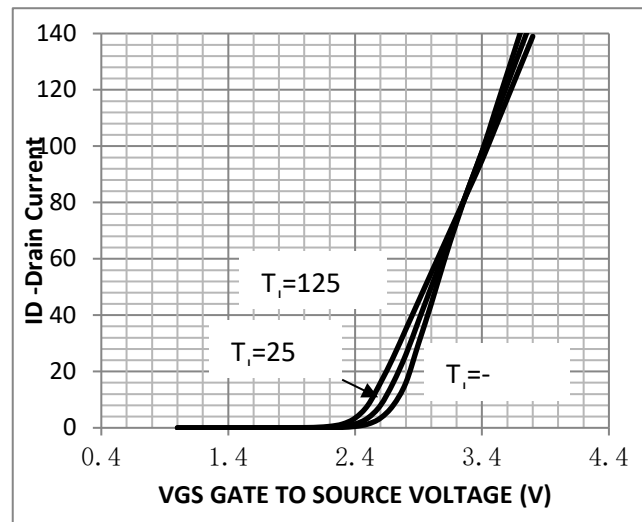


Figure 11. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

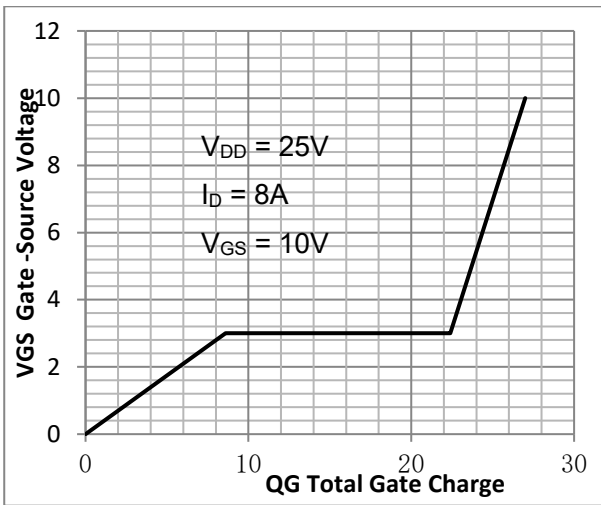


Fig.12 Capacitance Variation

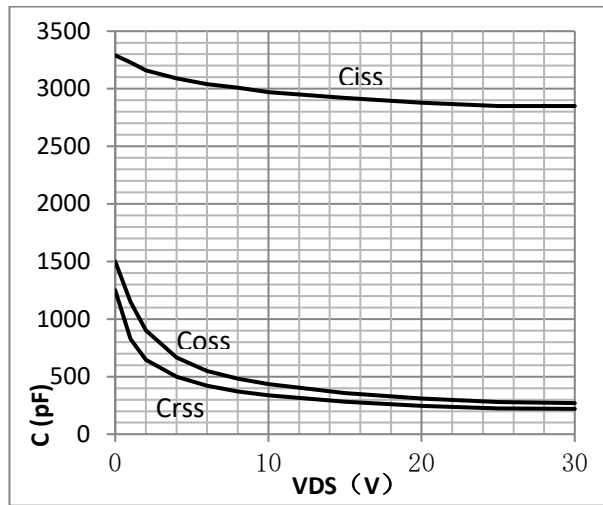


Fig.13 Switching Time Measurement Circuit

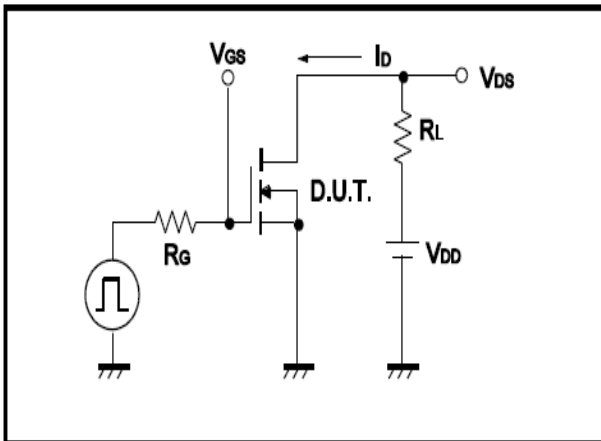


Fig.14 Gate Charge Waveform

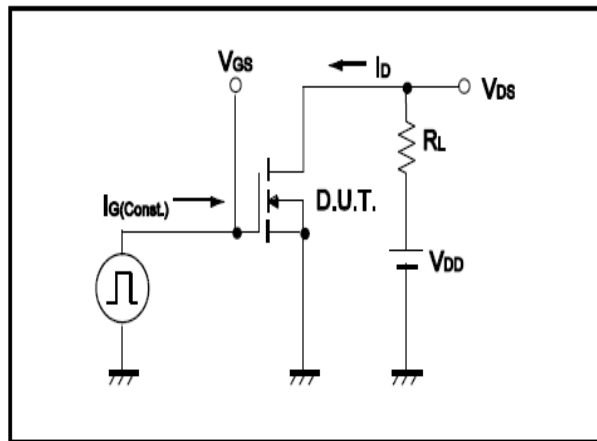


Fig.15 Avalanche Measurement Circuit

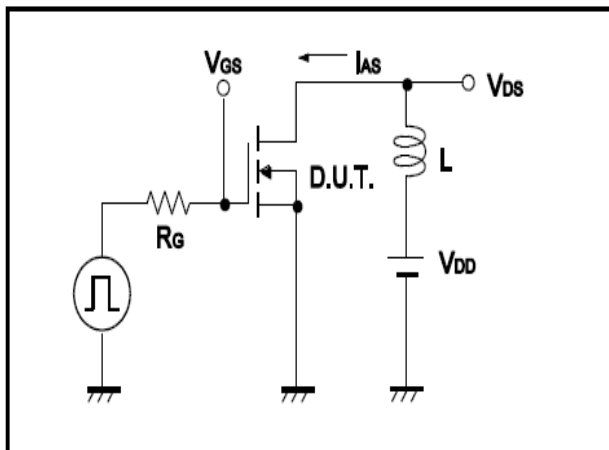


Fig.16 Avalanche Waveform

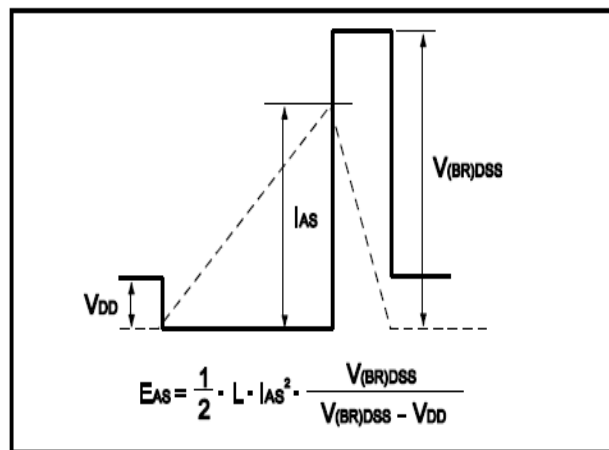
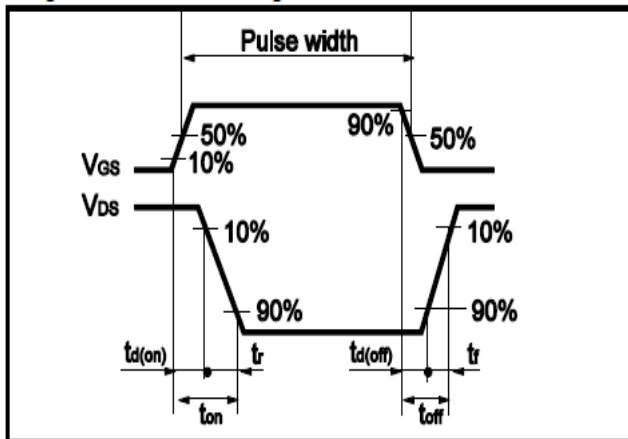


Fig.17 Gate Charge Waveform





•Dimensions(TO-251)

Unit: mm

SYMBOL	min	max	SYMBOL	min	max
A	2.10	2.50	D	6.35	6.80
A1	0.95	1.30	D1	5.10	5.50
B	0.80	1.25	E	5.30	6.30
b	0.50	0.80	e	2.24	2.35
b1	0.70	0.90	E1	4.43	4.73
c	0.45	0.60	L	7.00	9.40
c1	0.45	0.60			

